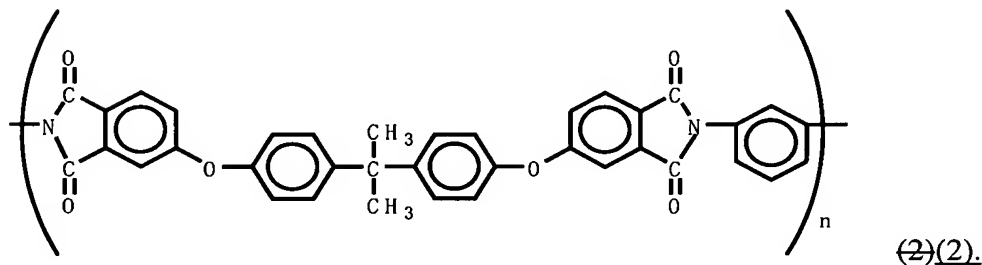
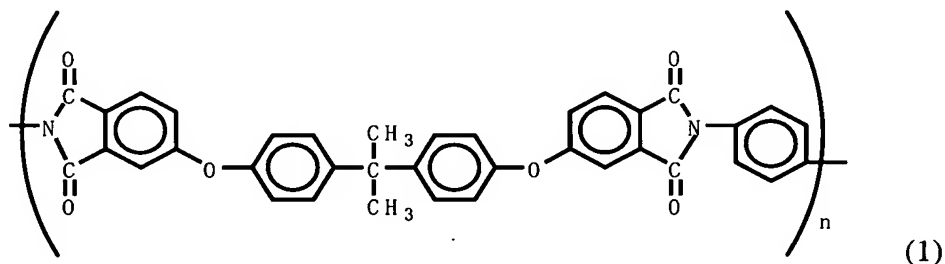


Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A film comprising (A-1) a polyetherimide resin having repeating units of the following structural formula (1), (A-2) a polyetherimide resin having repeating units of the structural formula (2), (B) a polyarylketone resin having a melting peak temperature of 260 degrees C or higher, and a filler in an amount of from 5 to 50 parts by weight, based on total 100 parts by weight of (A-1), (A-2) and (B), wherein a weight ratio of the resin components, [(A-1)+ (A-2)]/(B), ranges from 70/30 to 30/70 and a weight ratio, (A-1)/ (A-2), ranges from 70/30 to ~~30/70~~30/70;



2. (Original) The film according to claim 1, wherein the amount of the filler ranges from 10 to 45 parts by weight, based on total 100 parts by weight of (A-1), (A-2) and (B), and the weight ratio, [(A-1)+ (A-2)]/(B), ranges from 65/35 to 35/65 and the weight ratio, (A-1)/ (A-2), ranges from 65/35 to 35/65.

3. (Original) The film according to claim 1, wherein the amount of the filler ranges from 20 to 40 parts by weight, based on total 100 parts by weight of (A-1), (A-2) and (B), and the weight ratio, $[(A-1) + (A-2)]/(B)$, ranges from 65/35 to 45/55 and the weight ratio, $(A-1)/(A-2)$, ranges from 65/35 to 50/50.

4. (Previously Presented) A metal laminate comprising the film according to claim 1 and a metal body laminated on at least one side of said film.

5. (Original) The metal laminate according to claim 4, wherein the metal body comprises copper, aluminum, or stainless steel.

6. (Previously Presented) A multilayered board comprising at least two copper laminated films, each comprising the film according to claim 1 and a copper foil laminated on one side of said film.

7. (Original) A resin composition comprising (A-1) a polyetherimide resin having repeating units of the structural formula (1), (A-2) a polyetherimide resin having repeating units of the structural formula (2), (B) a polyaryletherimide resin having a melting peak temperature of 260 degrees C or higher, and a filler in an amount of from 5 to 50 parts by weight, based on total 100 parts by weight of (A-1), (A-2) and (B), wherein a weight ratio of the resin components, $[(A-1) + (A-2)]/(B)$, ranges from 70/30 to 30/70 and a weight ratio, $(A-1)/(A-2)$, ranges from 70/30 to 30/70.

8. (Previously Presented) A metal laminate comprising the film according to claim 2 and a metal body laminated on at least one side of said film.

9. (Previously Presented) A metal laminate comprising the film according to claim 3 and a metal body laminated on at least one side of said film.

10. (Previously Presented) A multilayered board comprising at least two copper laminated films, each comprising the film according to claim 2 and a copper foil laminated on one side of said film.

11. (Previously Presented) A multilayered board comprising at least two copper laminated films, each comprising the film according to claim 3 and a copper foil laminated on one side of said film.

12. (New) The multilayered board according to claim 6, wherein at least two copper laminated films have been heat bonded at a temperature of 260 degrees C or lower.